

Title (en)  
ULTRA-HARD COMPOSITE LAYERS ON METAL SURFACES AND METHOD FOR PRODUCING THE SAME

Title (de)  
ULTRAHARTE KOMPOSITSCHICHTEN AUF METALLOBERFLÄCHEN UND VERFAHREN ZU IHRER HERSTELLUNG

Title (fr)  
COUCHES COMPOSITES ULTRADURES APPLIQUÉES SUR DES SURFACES MÉTALLIQUES ET PROCÉDÉ DE PRODUCTION DE CES COUCHES

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Abstract (en)  
[origin: US2010178491A1] The invention relates to a metal substrate comprising an ultra-hard composite layer consisting of an inorganic, vitreous matrix containing one or more abrasive fillers. According to the invention, the diameter of the filler particles or, if the filler particles have a platelet-type form, the thickness of the filler particles is less than the layer thickness of the composite layer.

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